

**REMARKS**

This is in response to the Office Action dated February 11, 2008. Claims 1-2 and 4-16 are pending.

Claim 1 stands rejected under Section 103(a) as being allegedly unpatentable over Seko (US 2002/0043713) in view of Papathomas. This Section 103(a) rejection is respectfully traversed for at least the following reasons.

Claim 1 requires that “the resin is configured so that pressing of the semiconductor element against the interconnection pattern through the resin after the resin has been provided on the substrate forms a resin fillet, the resin fillet extending no more than about half-way up a sidewall of the semiconductor element and the resin fillet sealing the projecting electrode in electrical contact with the interconnection pattern; wherein the projecting electrode is composed of metal and does not contain solder; and wherein the insulating substrate is a polyimide-based insulating tape that is freely bendable and that has a thickness within a range of 15 to 40  $\mu\text{m}$ .” The cited art fails to disclose or suggest this subject matter.

Seko in Fig. 3 allegedly discloses insulating substrate 4, semiconductor element 1, resin 3, wiring pattern 5, and solder resist 6. The Examiner cites to Papathomas and contends that it would have been obvious to have used an anti-repellant in the resin in the device of Seko. The Examiner further argues that use of Papathomas’ material in Seko would result in the resin fillet extending no more than half-way up the sidewall of the semiconductor element.

However, claim 1 requires that the *projecting electrode is composed of metal and does not contain solder*. E.g., see page 17, lines 2-3 of the instant specification. The cited art fails to disclose or suggest this subject matter, and one of ordinary skill in the art would never have modified the cited art to meet claim 1 in this respect.

Papathomas relates to a **solder** interconnection structure which uses a particular material relied on by the Examiner for the express purpose of improving fatigue life and stability of **solder** interconnections (e.g., see Papathomas at col. 1, lines 25-31; col. 3, lines 52-67). The only reason why Papathomas uses the material he discloses is to improve life and stability of “solder” interconnections. Because claim 1 requires that the projecting electrode (6) is composed of metal and does not contain solder, there would be no reason why one of ordinary skill in the art would ever use the material and technique of Papathomas. This is because one of ordinary skill in the art would only use the material of Papathomas for solder connections – not connections involving metal such as gold or the like which does not include solder. Thus, any possible combination would never have been made by one of ordinary skill in the art.

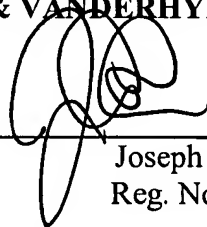
Claims 7, 15 and 16 define over the cited art in a similar manner.

It is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

Respectfully submitted,

**NIXON & VANDERHYE P.C.**

By: \_\_\_\_\_



Joseph A. Rhoa  
Reg. No. 37,515

JAR:caj  
901 North Glebe Road, 11th Floor  
Arlington, VA 22203-1808  
Telephone: (703) 816-4000  
Facsimile: (703) 816-4100